

RELIABILITY TEST DATA

Product name : S-93L76AD0I-T8TxU

Package type : 8-Pin TSSOP

| No. | Test item | Test Condition | Test Time | r/n |
|-----|--|---|--------------------------|------|
| 1 | High Temperature Operation | Ta=125 °C V _{CC} =Vopr max. | 1000 h | 0/22 |
| 2 | Write/Erase Cycle | Ta=85 °C V _{CC} =Vopr max. | 1×10 ⁶ cycles | 0/22 |
| 3 | High Temperature Bias | Ta=125 °C V _{CC} =Vabs max.×0.9 | 1000 h | 0/22 |
| 4 | #1 Temperature Humidity Bias | Ta=85 °C RH=85 % V _{CC} =Vabs max.×0.9 | 1000 h | 0/22 |
| 5 | #1 Un-saturated Pressure Cooker Bias | Ta=125 °C RH=85 % P=2×10 ⁵ Pa V _{CC} =Vabs max.×0.9 | 100 h | 0/22 |
| 6 | High Temperature Storage | Tstg max.=150 °C | 1000 h | 0/22 |
| 7 | Low Temperature Storage | Tstg min.=−65 °C | 1000 h | 0/22 |
| 8 | #1 Temperature Cycle (Gas phase) | Tstg max.=150 °C , Tstg min.=−65 °C (30 min each) | 200 cycles | 0/22 |
| 9 | #1 Thermal Shock (Liquid phase) | Tstg max.=150 °C , Tstg min.=−65 °C (5 min each) | 100 cycles | 0/22 |
| 10 | #1 Resistance to soldering heat - 1 (reflow) | T=260 °C , 10 s | 3 times | 0/22 |
| 11 | #1 Resistance to soldering heat - 2 (Solder iron) | T=380 °C , 5 s | Twice | 0/22 |
| 12 | #2 Solderability | T=230 °C Solder material ; Sn-3.0Ag-0.5Cu | 3 s | 0/11 |
| 13 | Whisker - 1 (Room Temperature Storage) | Ta=25±3 °C RH=40~70% criteria ; Whisker should be less than 50μm | 3 months | 0/10 |
| 14 | Whisker - 2 (Temperature Cycle) | Tstg max.=85 °C , Tstg min.=−40 °C (30 min each) criteria ; Whisker should be less than 50μm | 1000 cycles | 0/10 |
| 15 | Whisker - 3 (Temperature Humidity Storage) | Ta=60 °C RH=93 % criteria ; Whisker should be less than 50μm | 2000 h | 0/10 |
| 16 | Solder Joint Reliability (Temperature Cycle + shear test) | Tstg max.=125 °C , Tstg min.=−40 °C (30 min each) Solder material ; Sn-3.0Ag-0.5Cu criteria ;After temperature cycle test, keep strength for shear stress more than the 50 % of initial mean value. | 2000 cycles | 0/5 |
| 17 | Lead Strength (Pull test) | Pull force ; 1.0 N | 30 s | 0/11 |
| 18 | Lead Strength (Bending test) | Load ; 0.5 N 45 degree Bend a lead | Twice | 0/11 |

| | | | | |
|----|----------------------------|--|----------|------|
| 19 | ESD - 1 (Human Body Model) | V=±2000 V C=100 pF R=1.5 kΩ Ref. To V _{CC} / GND (5units for each direction) | 5 pulses | 0/20 |
| 20 | ESD - 2 (Machine Model) | V=±200 V C=200 pF R=0 Ω Ref. To V _{CC} / GND (5units for each direction) | 3 pulses | 0/20 |
| 21 | Latch Up | ±100 mA (V _{CLAMP} = Vopr max.) 10 ms pulse V _{CC} =Vopr max. | 1 pulse | 0/5 |

Remark : Vabs max. = Absolute maximum voltage , Vopr max. =Maximum operation voltage

: Each test designated # is performed after Pre-Treatment finished.

Pre-Treatment consists of High Temperature Storage , Temperature Humidity Storage and Soldering Heat. (See the table below.)

| Pre Treatment (#1) | | |
|---------------------|--------------------------------|---|
| High Temp. Storage | Temperature Humidity Storage | Soldering Heat |
| Ta=125 °C t=24 h | Ta=85 °C RH=85 % t=168 h | Infrared Reflow 3 times T=260 °C t=10 s |

| Pre Treatment (#2) | | |
|---------------------|--------------------------------|----------------|
| High Temp. Storage | Temperature Humidity Storage | Soldering Heat |
| Ta=125 °C t=24 h | Ta=105 °C RH=100 % t=8 h | — |